

### **Abstract of the Invention**

A method of forming a layered polishing pad is disclosed. The method includes double-laminating a subpad on opposing sides with respective adhesive layers and bonding a polishing pad top layer to the subpad via the upper adhesive layer. The polishing pad optionally includes a window. Because the subpad is double-laminated, an opening can be formed through both the top and bottom adhesive layers as well as the subpad. Thus, when bonded to a top polishing pad layer having a window, the result is a layered polishing pad with a through optical path that does not include an adhesive layer.